

**UNIQUE SILICONE GEL OFFERS COMPLIANCY, THERMAL RESISTANCE**

Tflex™ 300, at pressures of 50psi, will deflect to over 50% the original thickness. This high rate of compliance allows the material to “totally blanket” the component, enhancing thermal transfer. The material has a very low compression set enabling the pad to be reused many times.

Tflex™ 300, in achieving its stellar compliance, does not sacrifice thermal performance. With a thermal conductivity of 1.2 W/mK, low thermal resistances can be achieved at low pressures.

Tflex™ 300-H is offered with a hard, metallized liner option for easy handling and improved rework. The metallized liner's lower coefficient of friction also allows for easy assembly of parts that must slide together, such as a card into a chassis.

FEATURES AND BENEFITS

- Extreme compliance allows material to “totally blanket” component(s)
- Thermal conductivity of 1.2 W/mK
- Available in thicknesses from 0.020” - 0.200” (.5mm – 5.0mm)
- Low compression set enables the pad to be reused many times

APPLICATIONS

- Notebook and desktop computers
- Telecommunication hardware
- Flat panel displays
- Memory modules
- Power conversion equipment
- Set top box
- Lighting ballast
- Automotive electronics
- LED lighting
- Handheld electronics
- Optical disk drives
- Vibration dampening

global solutions: local support™

Americas: +1.888.246.9050

Europe: +49.(0).8031.2460.0

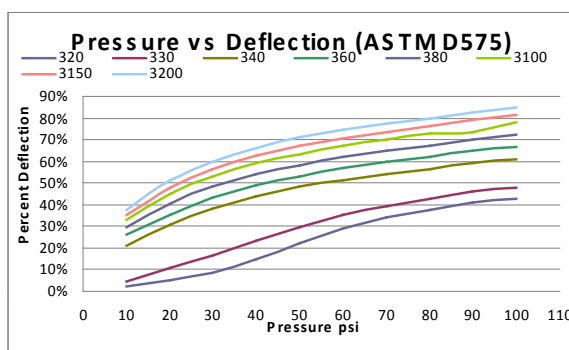
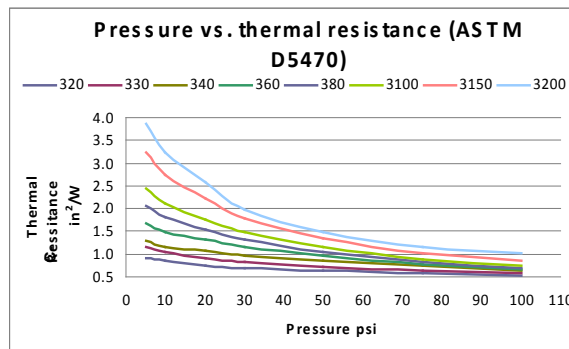
Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

TFLEX™ 300 TYPICAL PROPERTIES

	TFLEX™ 300	TEST METHOD
Construction	Filled silicone elastomer	NA
Color	Light green	Visual
Thermal Conductivity	1.2 W/mK	ASTM D5470
Hardness (Shore 00)	40 (at 3 second delay)	ASTM D2240
Density	1.78 g/cc	Helium Pycnometer
Thickness Range	0.020" - .200" (0.5 - 5.0mm)*	
Thickness Tolerance	±10%	
UL Flammability Rating	94 V0	UL
Temperature Range	-40°C to 160°C	NA
Volume Resistivity	10 ¹³ ohm-cm	ASTM D257
Outgassing TML	0.56%	ASTM E595
Outgassing CVM	0.10%	ASTM E595
Coefficient Thermal Expansion (CTE)	600 ppm/C	IPC-TM-650 2.4.24



STANDARD THICKNESSES

0.020 to 0.200-inch (0.5 to 5.0mm)*

0.020 to 0.200-inch thick material available in 0.010-inch (0.25mm) increments

*Inquire about availability of material and options above 0.200-inches

** FG (fiberglass) is standard for thicknesses 0.020" (0.50mm) and 0.030" (0.76mm)

OPTIONS

PET dielectric "H" liner available for applications where easy slide assembly is desirable

MATERIAL NAME AND THICKNESS

Tflex™ indicates elastomeric gap filler product line

3xxx indicates high recovery '3 series' 1.2 W/mK material

-DC1 designates proprietary tack eliminated coating

-H indicates hard PET liner option

EXAMPLES

Tflex™ 3120 = standard 0.120-inch thick Tflex™ 300 material

Tflex™ 3120DC1 = 0.120-inch thick material with DC1 coating

Tflex™ 3120H = 0.120-inch thick material with hard PET liner

THR-DS-TFLEX-300 0612

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2011 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights. Document A15293-00 Rev F, 06/2012.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9